L Number	Hits	Search Text	DB	Time stamp
I	177	(438/613.ccls. and resin) and (cure or thermoset\$5 or	USPAT;	2004/03/04 14:57
		uv or "exposure mask" or irradiat\$4)	US-PGPUB;	
		•	EPO;	
	!		DERWENT;	
			IBM TDB	
2	27	rcc and bump	USPĀT;	2004/03/04 16:35
_			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM TDB	
4	52	rcc and solder	USPAT;	2004/03/04 16:35
•			US-PGPUB;	200 2,00,01 20.00
			EPO;	
			DERWENT;	
			IBM TDB	
	83	((flip chip and regin) and photogongitive) and laminated	USPAT;	2004/03/04 11:42
-	63	((flip-chip and resin) and photosensitive) and laminated	US-PGPUB;	2004/03/04 11:42
			1	
			EPO;	
			DERWENT;	
	_	//GP 1	IBM_TDB	0004/00/00 17 00
-	4	((flip-chip and resin) and photosensitive) and rcc	USPAT;	2004/03/02 17:00
			US-PGPUB;	
			EPO;	
			DERWENT;	
	_	(0.5500.1700.1	IBM_TDB	0000/00/00/00
-	5	6255039.URPN.	USPAT	2003/03/16 09:36
-	11	("3319317" "3778900" "4642160" "4672020"	USPAT	2003/03/16 09:39
		"4915983" "4952528" "5334487" "5354593"		
		"5451721" "5595858" "5744285").PN.		
-	202	(flip-chip and resin) and photosensitive	USPAT;	2004/03/02 17:14
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	690	438/108.ccls.	USPAT;	2003/03/16 10:56
			US-PGPUB;	
			EPO;	
			DERWENT;	
		•	IBM_TDB	
	338	438/108.ccls. and resin	USPAT;	2004/03/02 17:25
			US-PGPUB;	
			EPO;	
·			DERWENT;	
		,	IBM_TDB	
	328	(438/108.ccls. and resin) not ((flip-chip and resin)	USPĀT;	2003/03/16 10:56
		and photosensitive)	US-PGPUB;	
	1	•	EPO;	
			DERWENT;	
			IBM TDB	
_	163	((438/108.ccls. and resin) not ((flip-chip and resin)	USPAT;	2004/03/02 17:25
		and photosensitive)) and (cure or thermoset\$5 or uv or	US-PGPUB;	
		"exposure mask" or irradiat\$4)	EPO;	
		esposare mask of madate 1/	DERWENT;	
			IBM_TDB	
<u>-</u>	0	20020070459.URPN.	USPAT	2003/03/16 10:36
L		20020010137.01414.	1 001711	1 2003/03/10 10.30

	700	1 400/610	LICDATE	0000/00/1/ 11 11
-	722	438/613.ccls.	USPAT;	2003/03/16 11:11
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	000010011
~	319	438/613.ccls. and resin	USPAT;	2003/03/16 11:11
		· ·	US-PGPUB;	
			EPO;	
			DERWENT;	
		.	IBM_TDB	
-	138	(438/613.ccls. and resin) and (cure or thermoset\$5 or	USPAT;	2004/03/04 14:57
		uv or "exposure mask" or irradiat\$4)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	95	((438/613.ccls. and resin) and (cure or thermoset\$5	USPAT;	2003/03/16 11:12
		or uv or "exposure mask" or irradiat\$4)) not (((US-PGPUB;	
		438/108.ccls. and resin) not ((flip-chip and resin) and	EPO;	
		photosensitive)) and (cure or thermoset\$5 or uv or	DERWENT;	
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)	IBM_TDB	
		and photosensitive)		
-	1455	438/637.ccls.	USPAT;	2003/03/16 11:11
			US-PGPUB;	
			EPO;	
			DERWENT;	:
			IBM_TDB	
-	86	438/637.ccls. and resin	USPAT;	2003/03/16 11:11
			US-PGPUB;	
	ļ		EPO;	
	Ì		DERWENT;	
			IBM_TDB	
-	82	(438/637.ccls. and resin) not (((438/613.ccls. and	USPAT;	2003/03/16 11:16
		resin) and (cure or thermoset\$5 or uv or "exposure mask"	US-PGPUB;	
		or irradiat\$4)) not (((438/108.ccls. and resin) not	EPO;	
		((flip-chip and resin) and photosensitive)) and (cure or	DERWENT;	
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not	IBM_TDB	
		((flip-chip and resin) and photosensitive)) not (((
		438/108.ccls. and resin) not ((flip-chip and resin) and		
		photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
		and photosensitive)		
-	33	((438/637.ccls. and resin) not (((438/613.ccls. and	USPAT;	2003/03/16 11:15
		resin) and (cure or thermoset\$5 or uv or "exposure mask"	US-PGPUB;	
		or irradiat\$4)) not (((438/108.ccls. and resin) not	EPO;	
		((flip-chip and resin) and photosensitive)) and (cure or	DERWENT;	
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not	IBM_TDB	
		((flip-chip and resin) and photosensitive)) not ((_	
		438/108.ccls. and resin) not ((flip-chip and resin) and		
}		photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
		and photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)		
-	30	rcc and solder	USPAT;	2003/03/16 11:17
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM TDB	
· · · · · · · · · · · · · · · · · · ·	L	<u> </u>		

25	(rcc and solder) not ((438/637.ccls. and resin) not (((USPAT;	2003/03/16 11:17
	438/613.ccls. and resin) and (cure or thermoset\$5 or	US-PGPUB;	
	uv or "exposure mask" or irradiat\$4)) not (((EPO;	
	438/108.ccls. and resin) not ((flip-chip and resin) and	DERWENT;	
	photosensitive)) and (cure or thermoset\$5 or uv or	IBM_TDB	
	"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
	and photosensitive)) not (((438/108.ccls. and resin)		
	not ((flip-chip and resin) and photosensitive)) and (cure		
	or thermoset\$5 or uv or "exposure mask" or irradiat\$4))		
	not ((flip-chip and resin) and photosensitive)) not (((
	438/613.ccls. and resin) and (cure or thermoset\$5 or uv		
	or "exposure mask" or irradiat\$4)) not (((438/108.ccls.		
	and resin) not ((flip-chip and resin) and photosensitive))		
	and (cure or thermoset\$5 or uv or "exposure mask" or		
	irradiat\$4)) not ((flip-chip and resin) and		
	photosensitive)) not (((438/108.ccls. and resin) not		
	((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not		
	((flip-chip and resin) and photosensitive)		·
19		USPAT;	2004/03/04 16:32
	rec and bump	US-PGPUB;	2004/03/04 10.32
		EPO;	
		DERWENT;	
		IBM TDB	

				
-	8	(rcc and bump) not ((rcc and solder) not ((USPAT;	2003/03/16 11:17
		438/637.ccls. and resin) not (((438/613.ccls. and	US-PGPUB;	
		resin) and (cure or thermoset\$5 or uv or "exposure mask"	EPO;	
		or irradiat\$4)) not (((438/108.ccls. and resin) not	DERWENT;	
		((flip-chip and resin) and photosensitive)) and (cure or	IBM TDB	
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not	10100	
		· · · · · · · · · · · · · · · · · · ·		
		((flip-chip and resin) and photosensitive)) not (((
		438/108.ccls. and resin) not ((flip-chip and resin) and		
		photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
		and photosensitive)) not (((438/613.ccls. and resin)		
		and (cure or thermoset\$5 or uv or "exposure mask" or		
		• • • • • • • • • • • • • • • • • • •		
		irradiat\$4)) not (((438/108.ccls. and resin) not		
		((flip-chip and resin) and photosensitive)) and (cure or		
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not		
		((flip-chip and resin) and photosensitive)) not (((
		438/108.ccls. and resin) not ((flip-chip and resin) and		
		photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
]				
		and photosensitive)) not ((438/637.ccls. and resin)		
		not (((438/613.ccls. and resin) and (cure or		
1		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not		
		(((438/108.ccls. and resin) not ((flip-chip and resin)		
		and photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
		and photosensitive)) not (((438/108.ccls. and resin)		
		•		
		not ((flip-chip and resin) and photosensitive)) and (cure		
		or thermoset\$5 or uv or "exposure mask" or irradiat\$4))		
		not ((flip-chip and resin) and photosensitive)) not (((
		438/613.ccls. and resin) and (cure or thermoset\$5 or uv		
		or "exposure mask" or irradiat\$4)) not (((438/108.ccls.		
		and resin) not ((flip-chip and resin) and photosensitive))		
		and (cure or thermoset\$5 or uv or "exposure mask" or		
		irradiat\$4)) not ((flip-chip and resin) and		
		photosensitive)) not (((438/108.ccls. and resin) not		
		((flip-chip and resin) and photosensitive)) and (cure or		
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not		
		((flip-chip and resin) and photosensitive)		,
-	3147	flip-chip and resin	USPAT;	2004/03/02 17:01
			US-PGPUB;	
			EPO;	
-			DERWENT;	
			IBM_TDB	
	7	((flip ship and resin) and phatagonalding) and the	_	2004/02/02 17.01
-	/	((flip-chip and resin) and photosensitive) and rcc	USPAT;	2004/03/02 17:01
]		US-PGPUB;	
1			EPO;	
			DERWENT;	
			IBM TDB	
1.	277	(flip-chip and resin) and photosensitive	USPAT;	2004/03/02 17:15
	[~~	The state and tooking and photosociolities	US-PGPUB;	200 400/02 11.13
			·	
]			EPO;	
]			DERWENT;	
			IBM_TDB	
-	446	438/108.ccls. and resin	USPAT;	2004/03/02 17:25
		۶	US-PGPUB;	
		,	EPO;	
	}		DERWENT:	
			· · · · · · · · · · · · · · · · · · ·	
L			IBM_TDB	<u> </u>

-	208	((438/108.ccls. and resin) not ((flip-chip and resin)	USPAT;	2004/03/02 17:26
		and photosensitive)) and (cure or thermoset\$5 or uv or	US-PGPUB;	
		"exposure mask" or irradiat\$4)	EPO;	
			DERWENT;	
			IBM_TDB	
-	117	((flip-chip and resin) and photosensitive) and laminated	USPAT;	2004/03/04 11:43
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM TDB	

L Number	Hits	Search Text	DB	Time stamp
1	177	(438/613.ccls. and resin) and (cure or thermoset\$5 or	USPAT;	2004/03/04 14:57
		uv or "exposure mask" or irradiat\$4)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
2	27	rcc and bump	USPAT;	2004/03/04 16:35
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
4	52	rcc and solder	USPAT;	2004/03/04 16:35
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
5	41	((438/637.ccls. and resin) not (((438/613.ccls. and	USPAT;	2004/03/04 17:16
		resin) and (cure or thermoset\$5 or uv or "exposure mask"	US-PGPUB;	
		or irradiat\$4)) not (((438/108.ccls. and resin) not	EPO;	
		((flip-chip and resin) and photosensitive)) and (cure or	DERWENT;	
		thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not	IBM_TDB	
		((flip-chip and resin) and photosensitive)) not (((
		438/108.ccls. and resin) not ((flip-chip and resin) and		
		photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)) not ((flip-chip and resin)		
		and photosensitive)) and (cure or thermoset\$5 or uv or		
		"exposure mask" or irradiat\$4)		